

Development of a Monolithic Active Pixel Detector for a Super-B factory

Marlon Barbero, University of Hawaii

On behalf of the Belle Pixel Group

KEK, Krakow INP, Univ. of Hawaii, Tsukuba Univ.

DPF Riverside – 27-31 August 2004



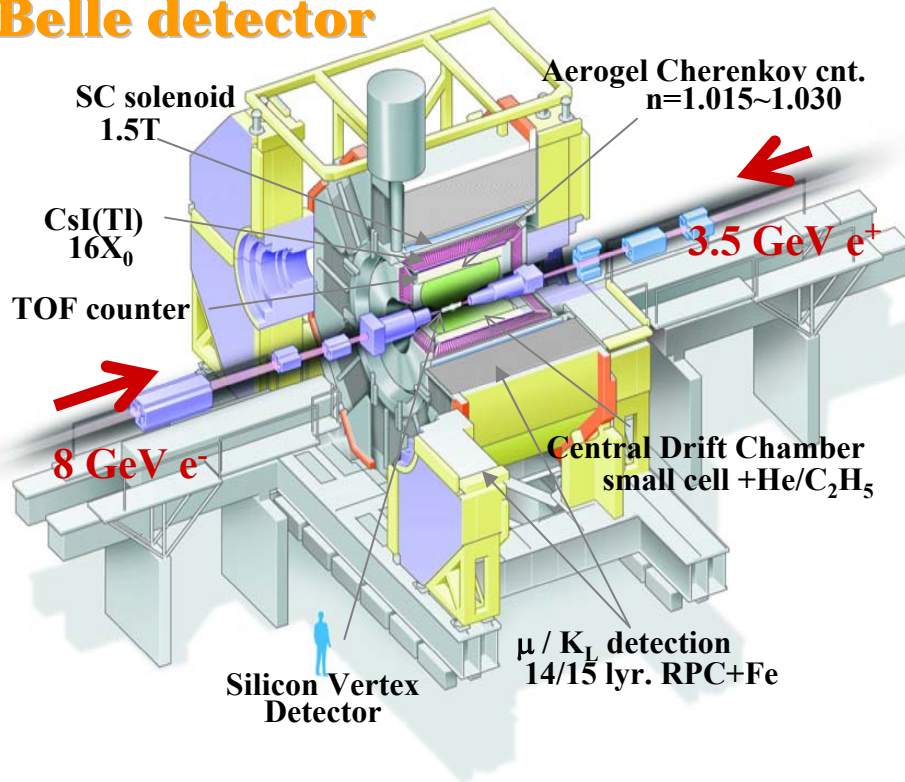
Outline

- **KEKB and BELLE detector.**
- **BELLE Silicon Vertex Detector / Super-BELLE perspective.**
- **Monolithic Active Pixel Sensor (MAPS) for BELLE upgrade.**
- **Principle of MAPS.**
- **Results of beam test on prototype MAPS, summer 2004.**
- **Critical R&D items.**
- **Plans for the near future.**
- **Highlights and conclusion.**



BELLE detector at KEKB

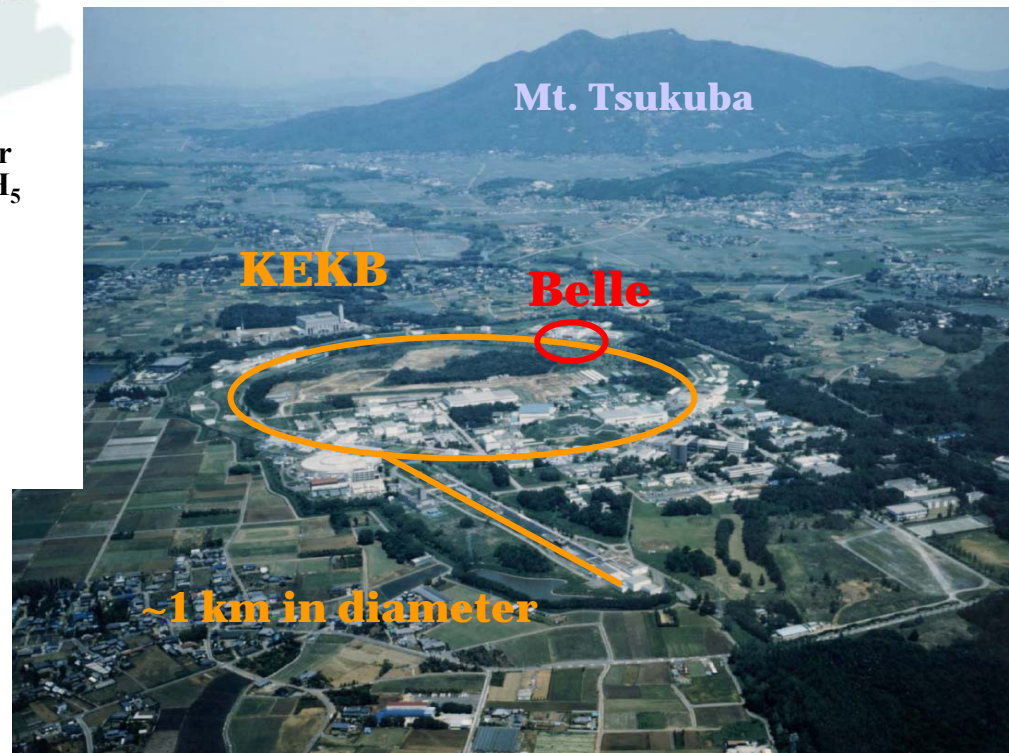
Belle detector



KEKB / Belle started operation in 1999

8 GeV e^- x 3.5 GeV e^+

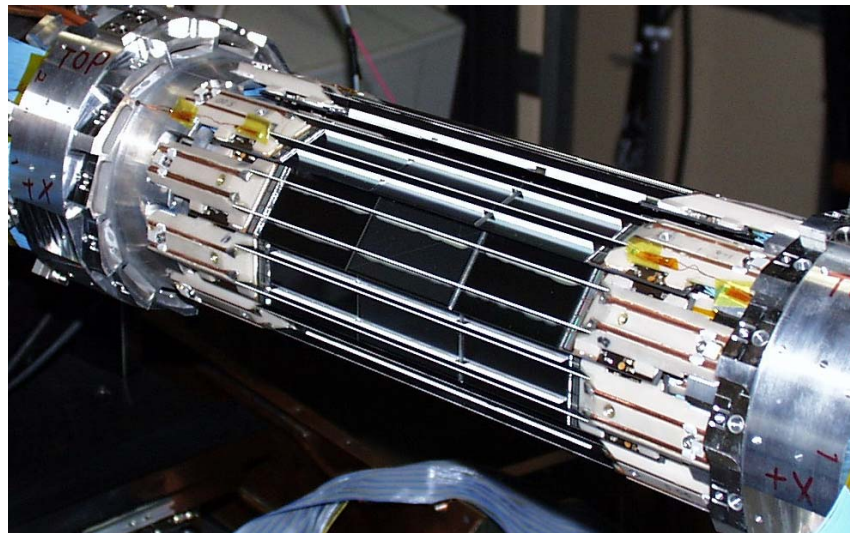
$L_{\text{peak}} = 1.39 \times 10^{34} \text{ cm}^{-2} \text{ sec}^{-1}$
(highest peak luminosity)



Integrated Luminosity
250 fb⁻¹ on-peak so far...
(~274 M. BB)

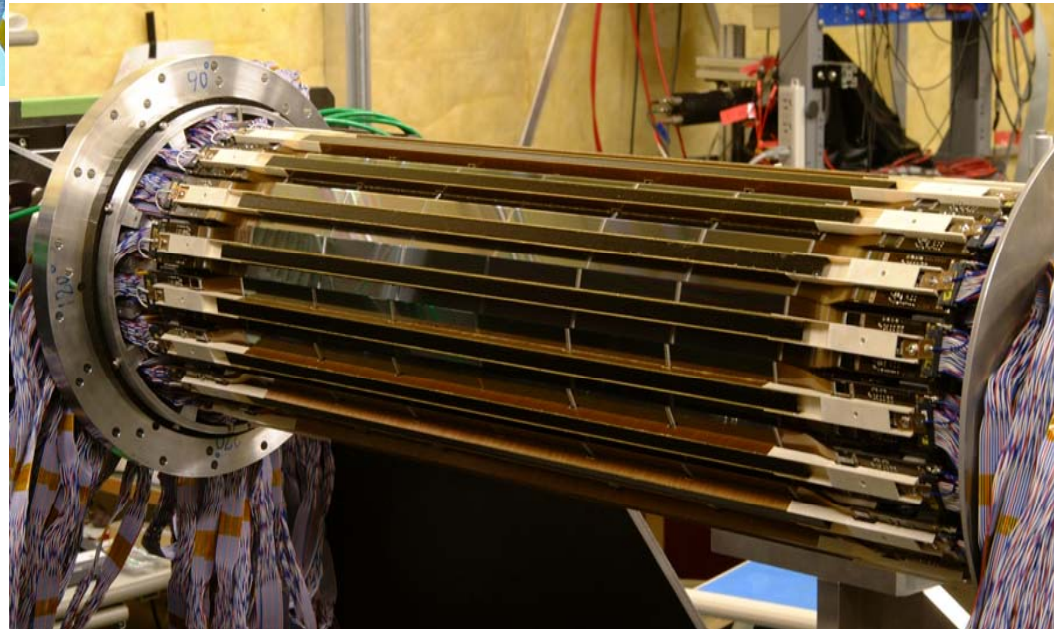


BELLE SVD1 → SVD2

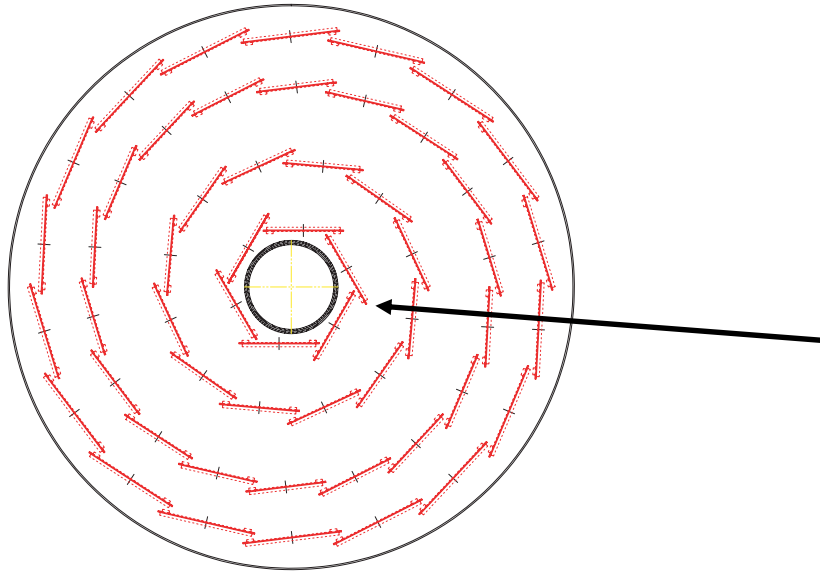


1st generation Silicon Vertex Detector (SVD1) → 2nd generation SVD (summer 2003)

Beam pipe radius: 20mm → 15mm
3 layers → 4 layers
~82K channels → ~110K channels
23° - 139° → 17° - 150° coverage
R=30/45/60 → R=20/43/70/88 (mm)
 $\sigma_{r\phi}$ 12 μ m/ σ_z 20 μ m



SVD with S-Belle perspective



Present : Belle SVD

~10% occupancy

200 Krad.yr⁻¹ cumulated

Upgrade: Super-Belle **$L \sim 1.10^{34} \rightarrow L \sim 5.10^{35} \text{ cm}^{-2} \cdot \text{s}^{-1}$**

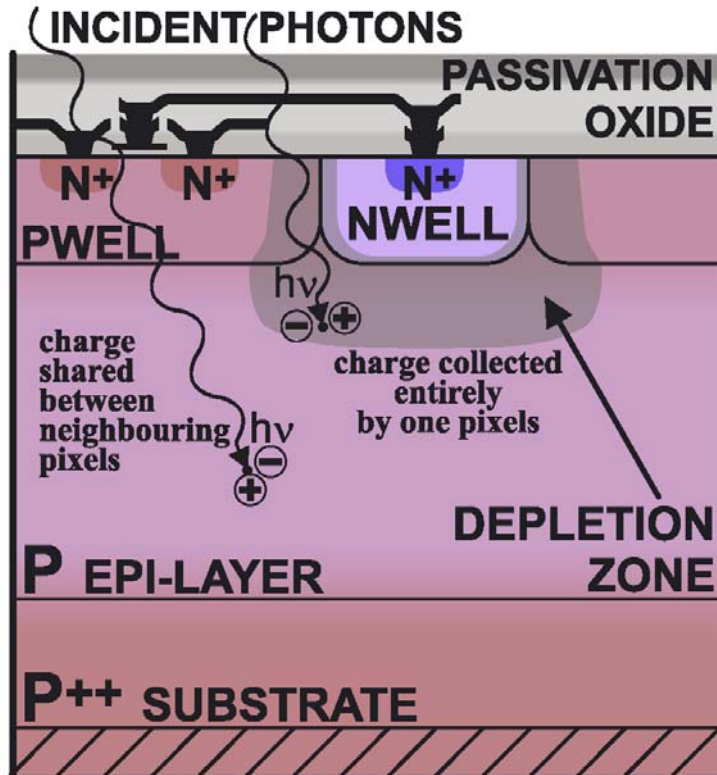
Background increase typ. x50 ! → **Occupancy / dose:**

Conventional solutions (Si strips) do not work.

Better impact parameter resolution?

MAPS Technology: Standard CMOS

“From digital camera to particle tracking device”



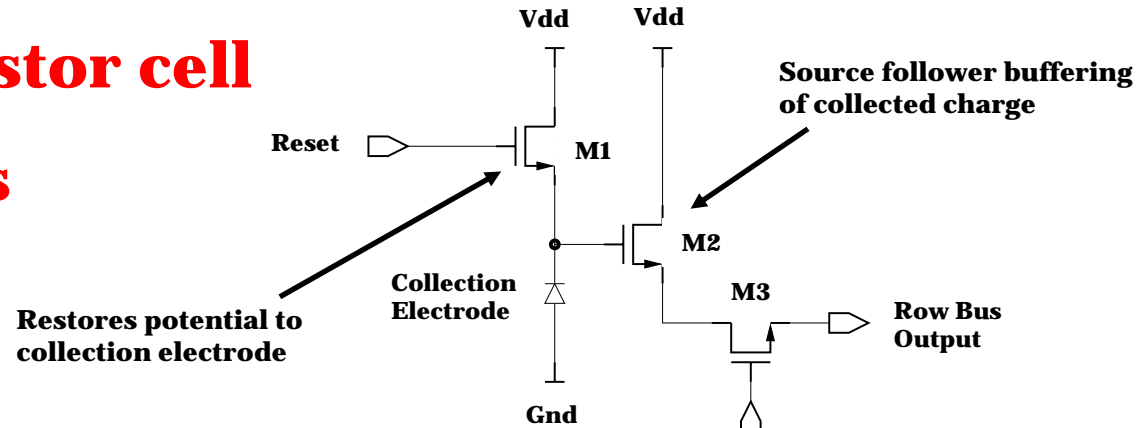
Key Features:

- q collection via thermal diffusion (**no HV**)
- “System on Chip” possible
- **NO bump bonding** (not a hybrid pixel detector)
- Could be **thinned**.
- **Standard CMOS**: good process control, low cost...

Cont. Acq. Pixels (CAP) 1 Prototype

CAP1: simple 3-transistor cell

TSMC 0.35 μ m Process



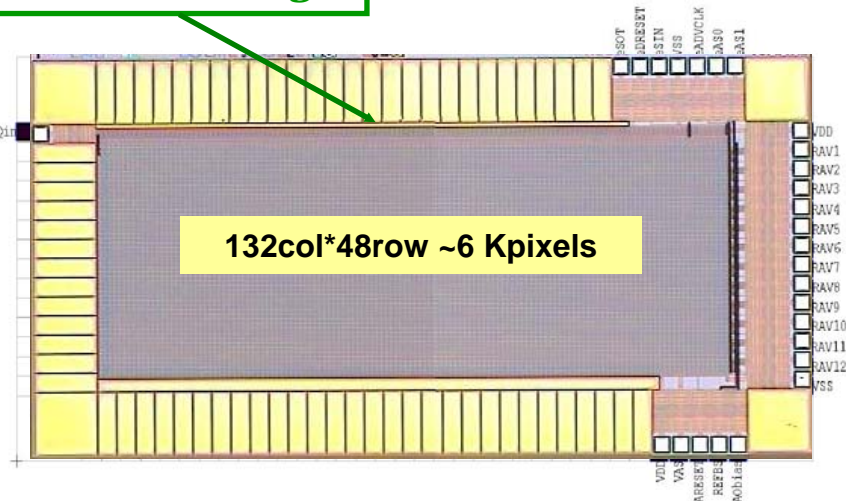
Pixel size:

22.5 μ m x 22.5 μ m

Column Ctrl Logic

1.8 mm

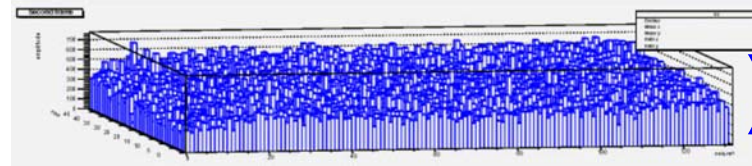
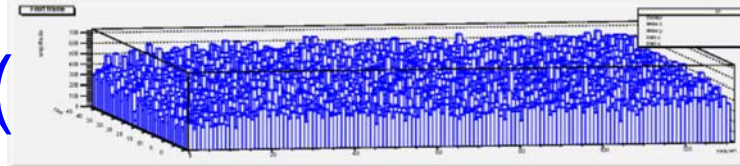
132col*48row ~6 Kpixels



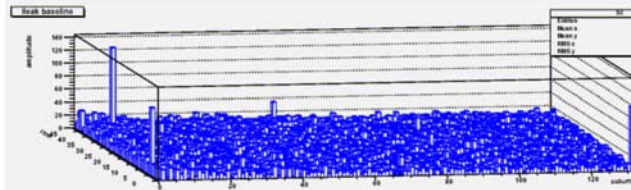
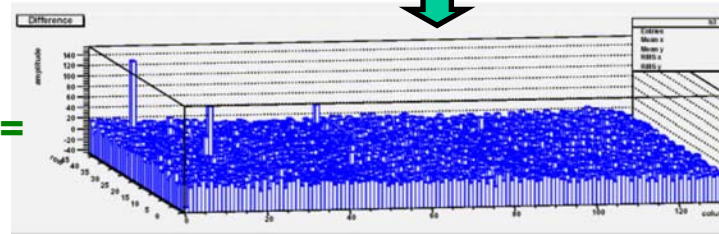
CAPs sample tested: all detectors (>15) function.



Correlated Double Sampling (CDS)



Frame 1 - Frame 2 =



- Leakage current Correction

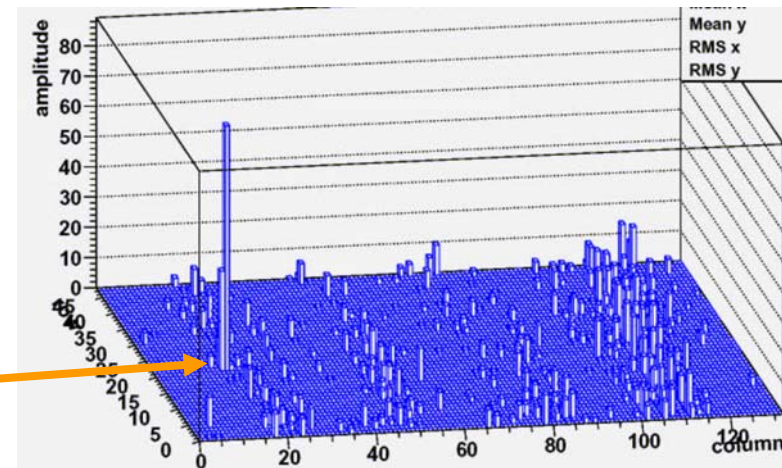
~fA leakage current (typ)

~18fA for hottest pixel shown

8ms integration

Can readout/process @ 20Hz ~ 16% live time (CAP1!)
Self-Triggering mode

Hit candidate!

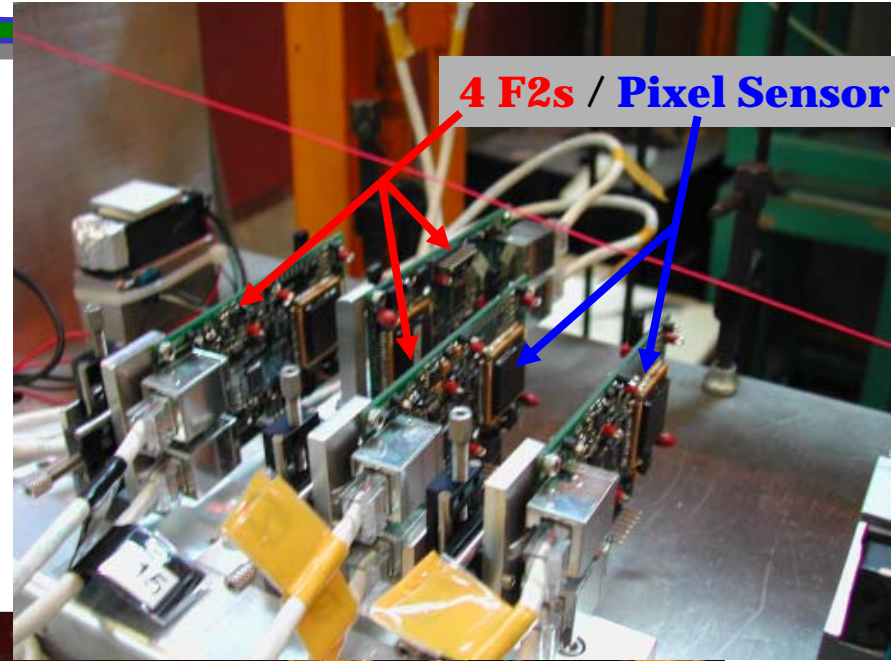


Jun.04 KEK Test Beam with pions

π^2 area



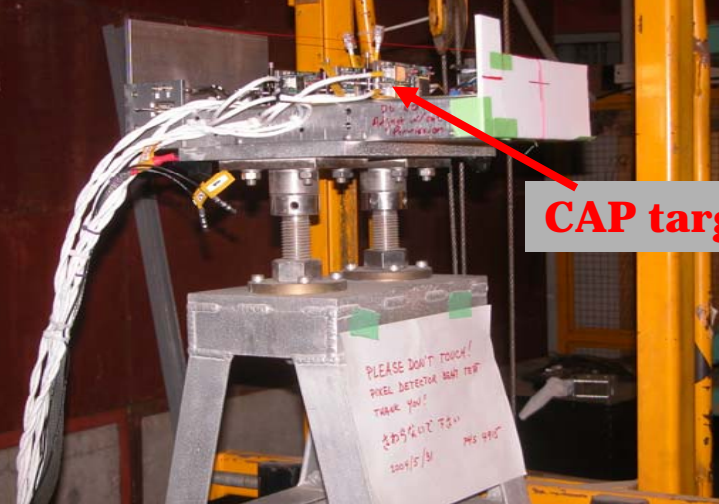
4 F2s / Pixel Sensor



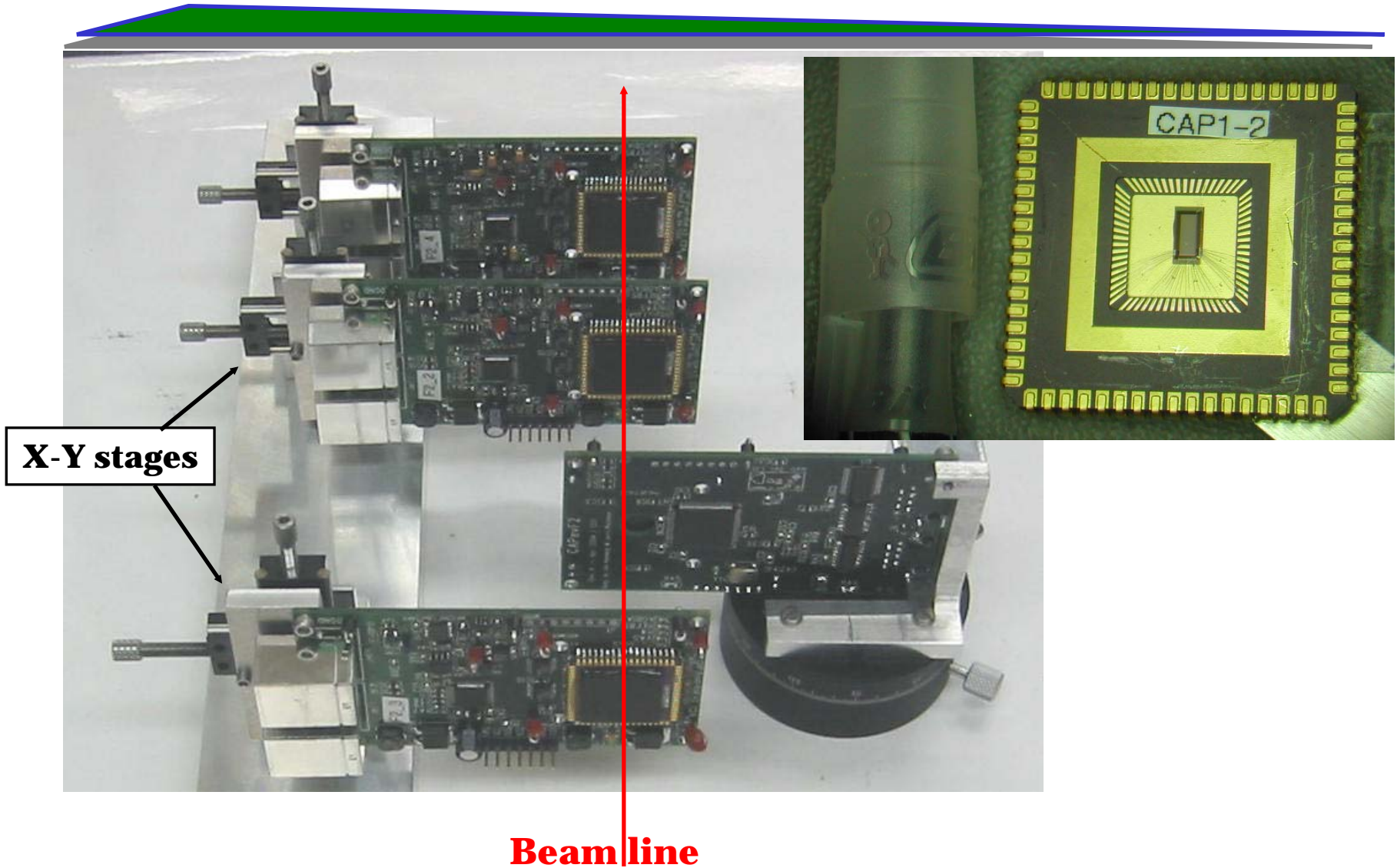
B-Board / DAQ



CAP targets !

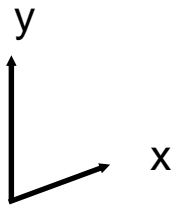
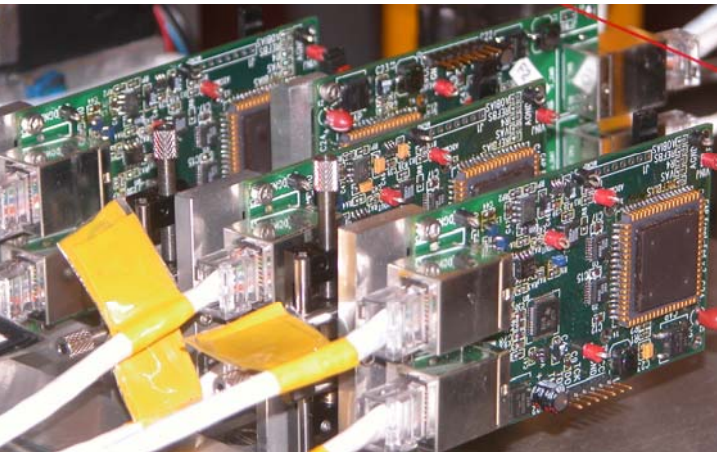


Beam test bench

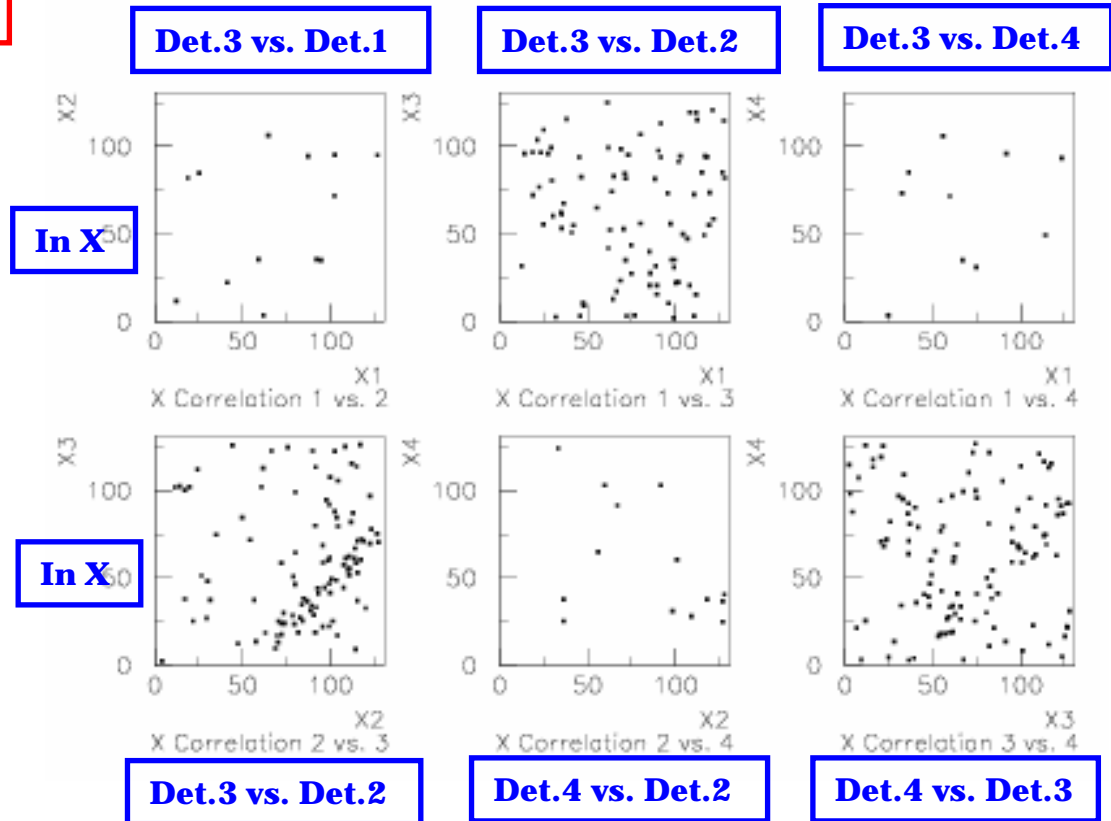


Initial “by eye”

~1mm x 3mm “rice grain”



Layer-by-layer correlations



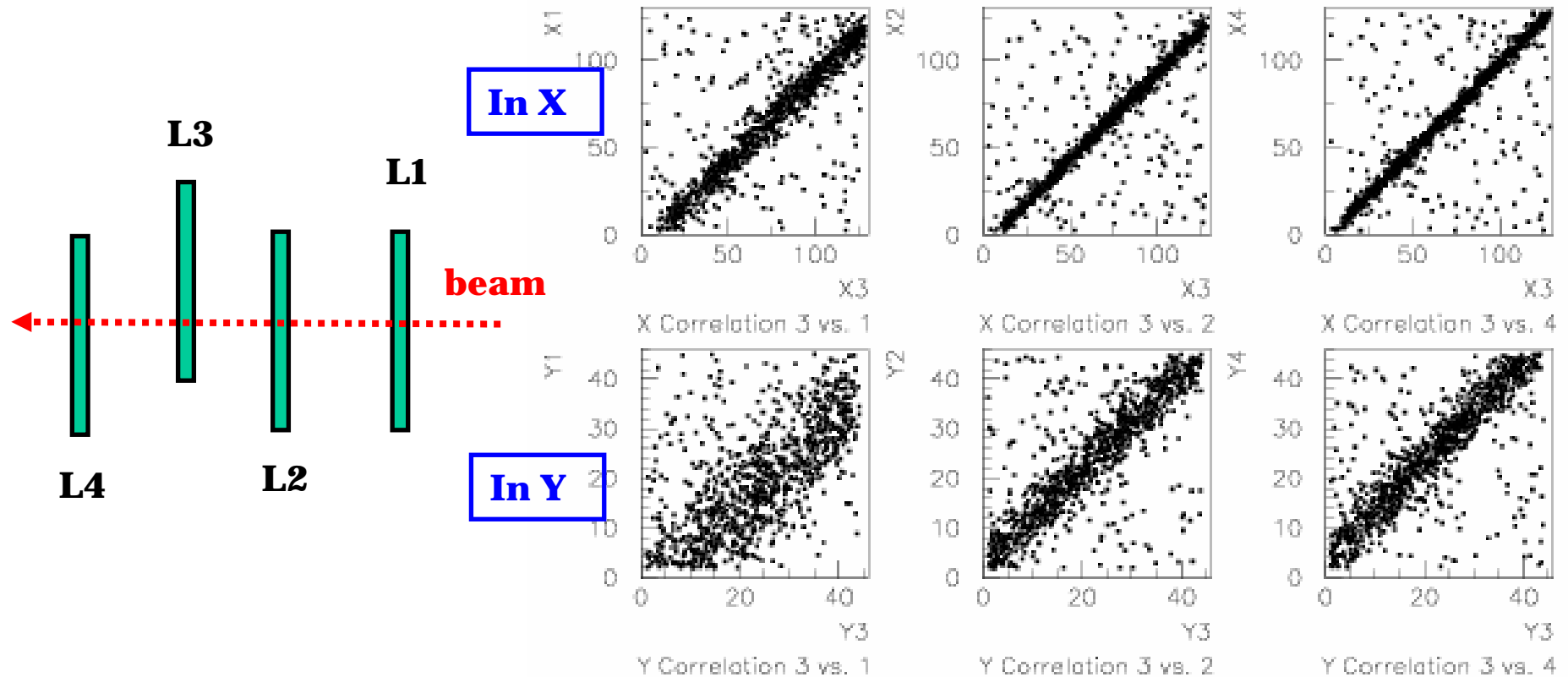
And after 4 iterations...

Improved Alignment

Det.3 vs. Det.1

Det.3 vs. Det.2

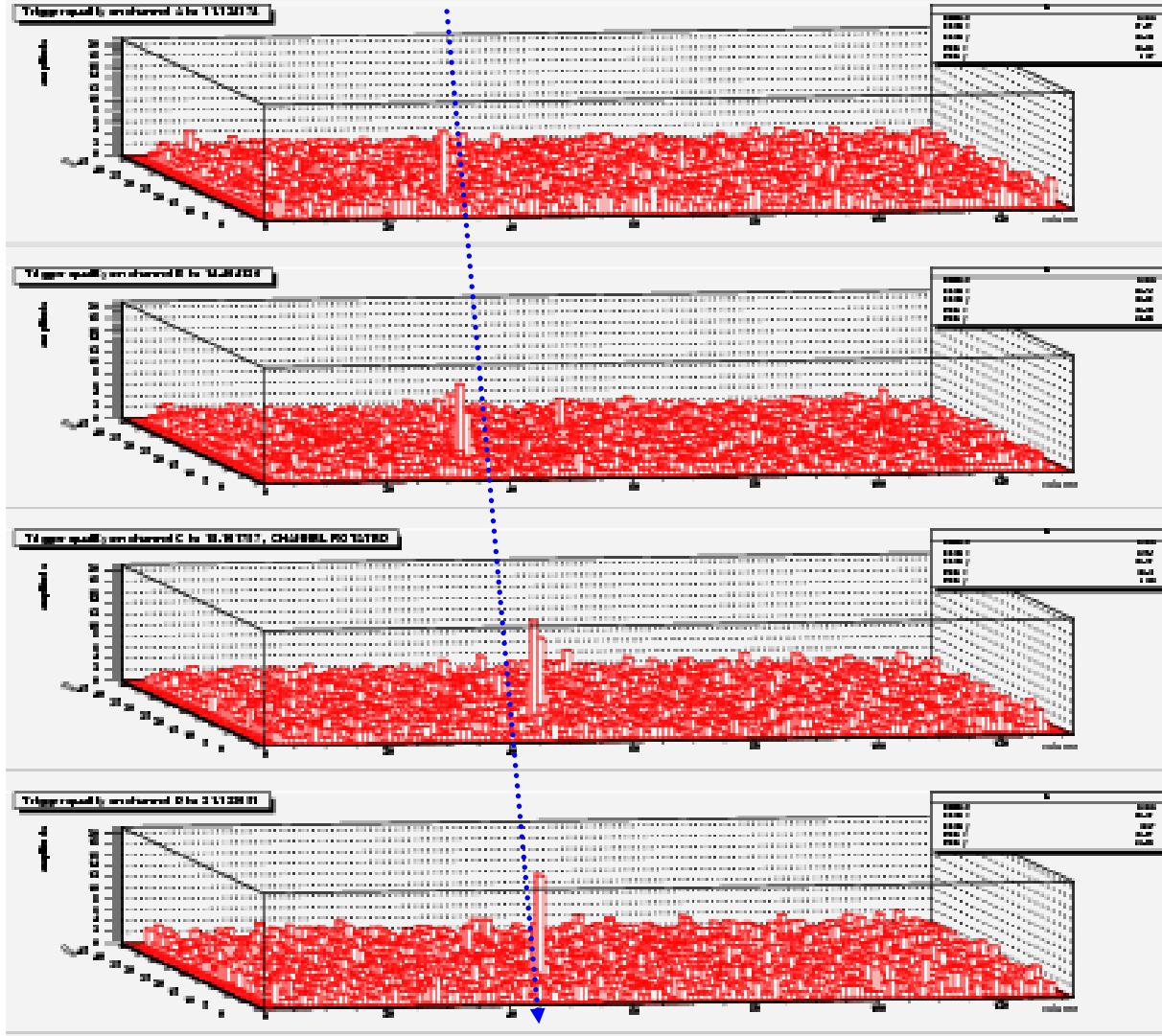
Det.3 vs. Det.4



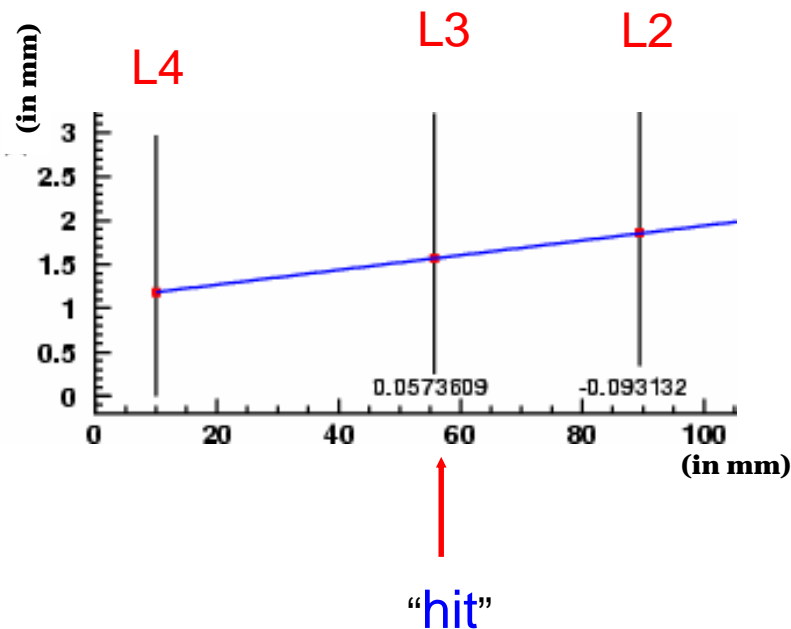
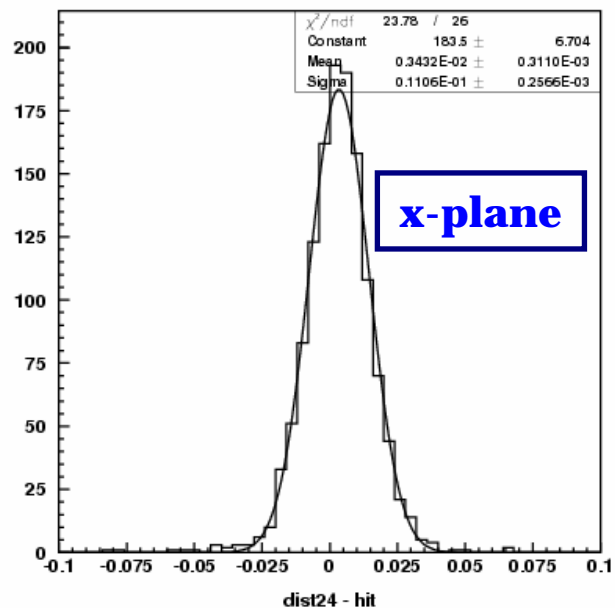
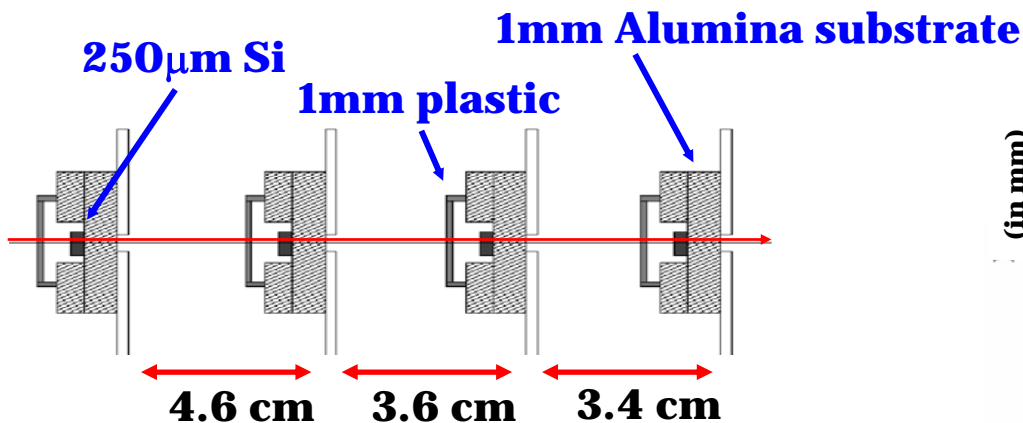
"online" plot



Hits! alignment proof



Hit resolution measurement



Current Residuals, @ 4GeV:

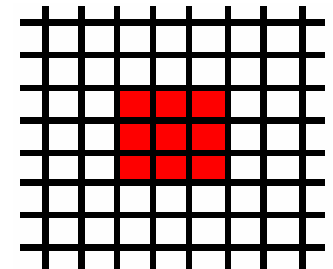
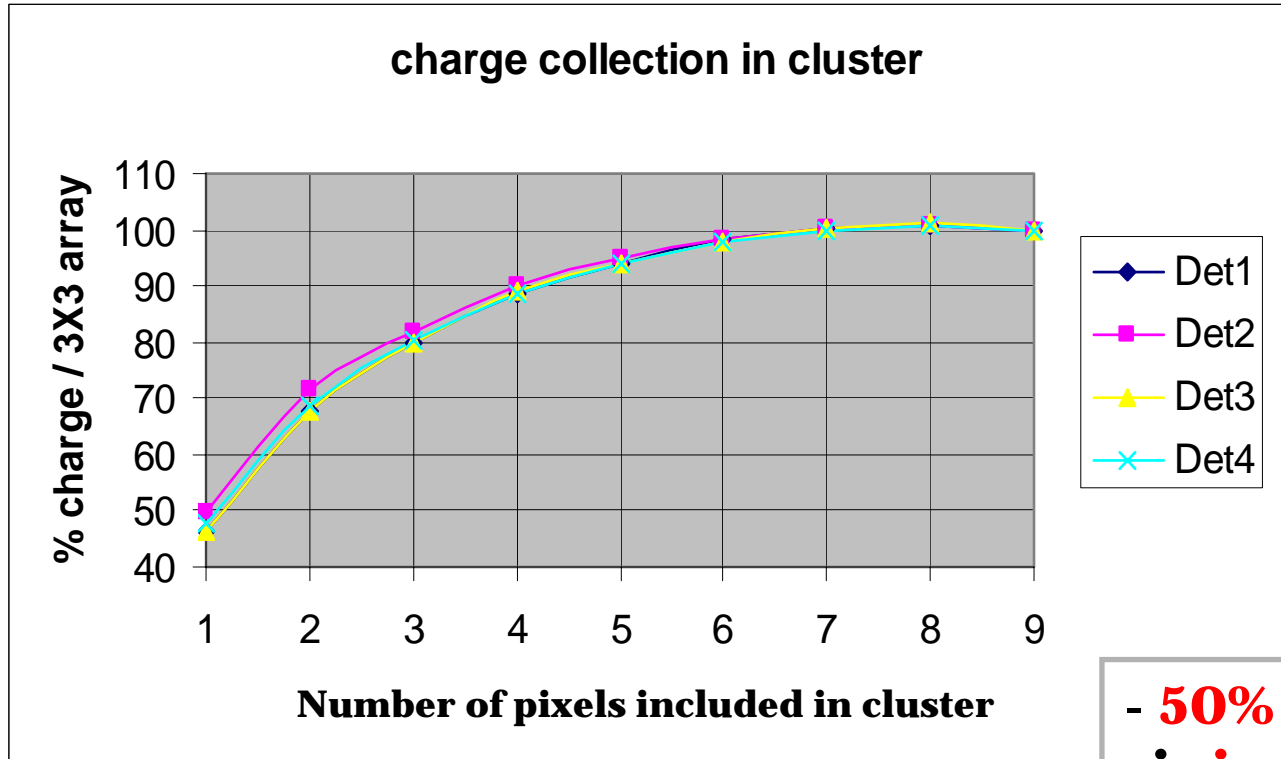
- **11 μ m** in x plane
- **14 μ m** in y plane

Charge Spread in CAPS

... still June 2004 beam test data...

(MPV of landau fit)

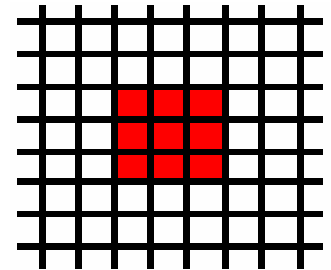
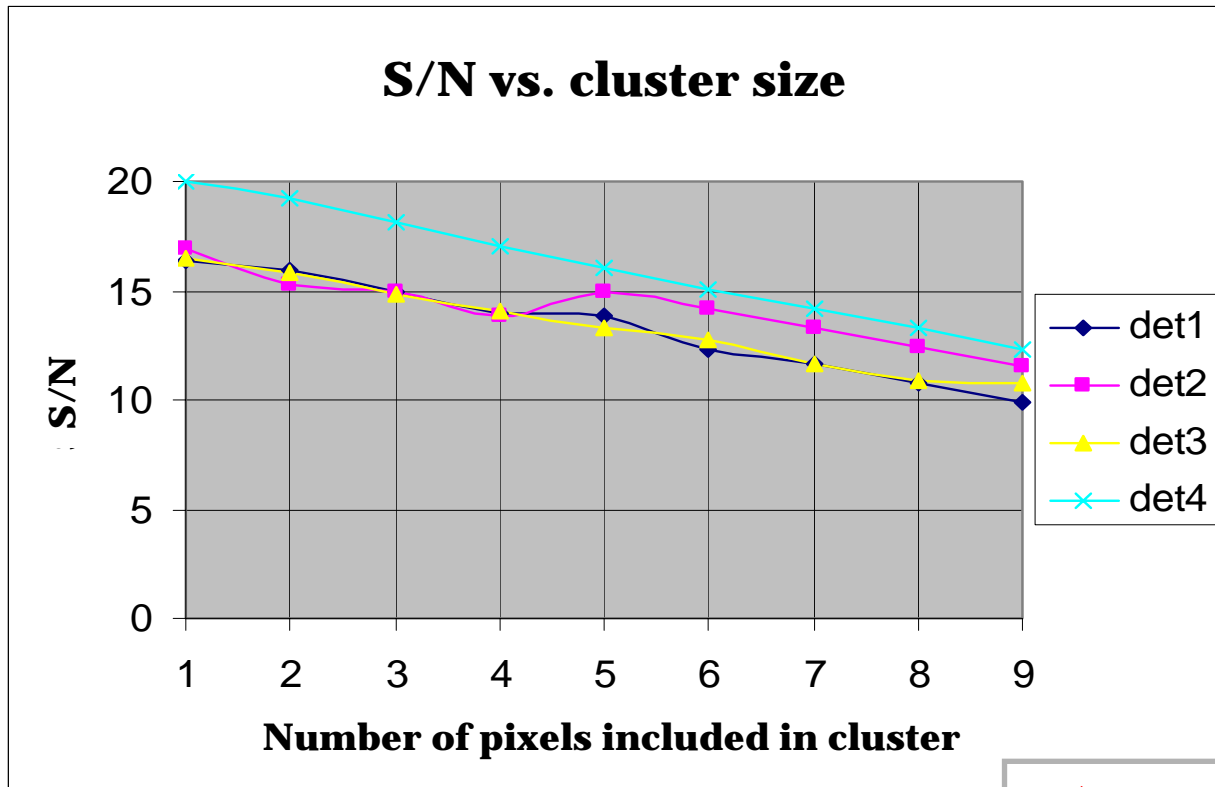
Hyp: charge entirely collected in 3X3 pixel array.



- **50%** of the charge is in the peak pixel.
- **90%** in the 4 largest.

S/N vs. Cluster Size

... still June 2004 beam test data...



**S/N peak signal
between 16 and 20.**

CAP1 / 8ms integration time

Four Critical R&D Items

1. Readout Speed

1. **Super-B**: CAP2, syst. archi., next main R&D topic
2. **Elsewhere**: STAR phase 1, LC, RAL efforts

2. Radiation Hardness

1. **Super-B**: low E e^-/γ CAP -- results shown next
2. **Elsewhere**: TESLA, STAR 10^{12} n_{eq} , >100kRad ionizing

3. Thin Detector – **LBNL**

4. Full-sized detector – **LEPSI**



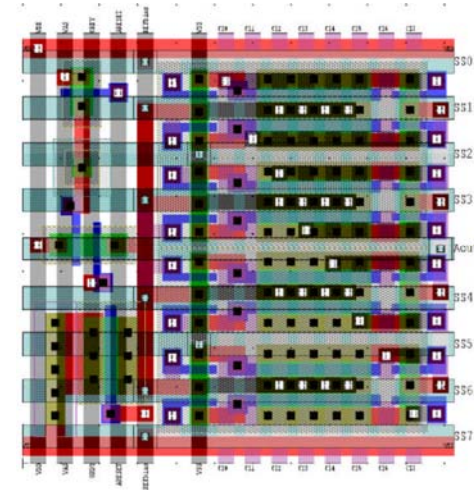
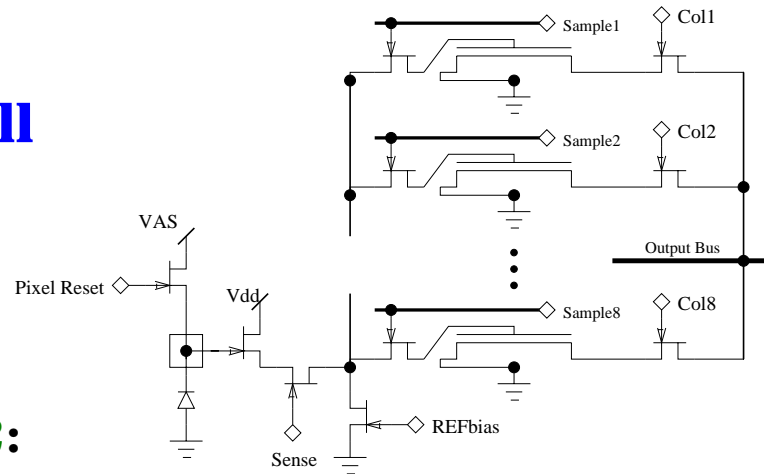
1. Increased readout speed: CAP2

CAP2: 8x mini-pipeline in each cell

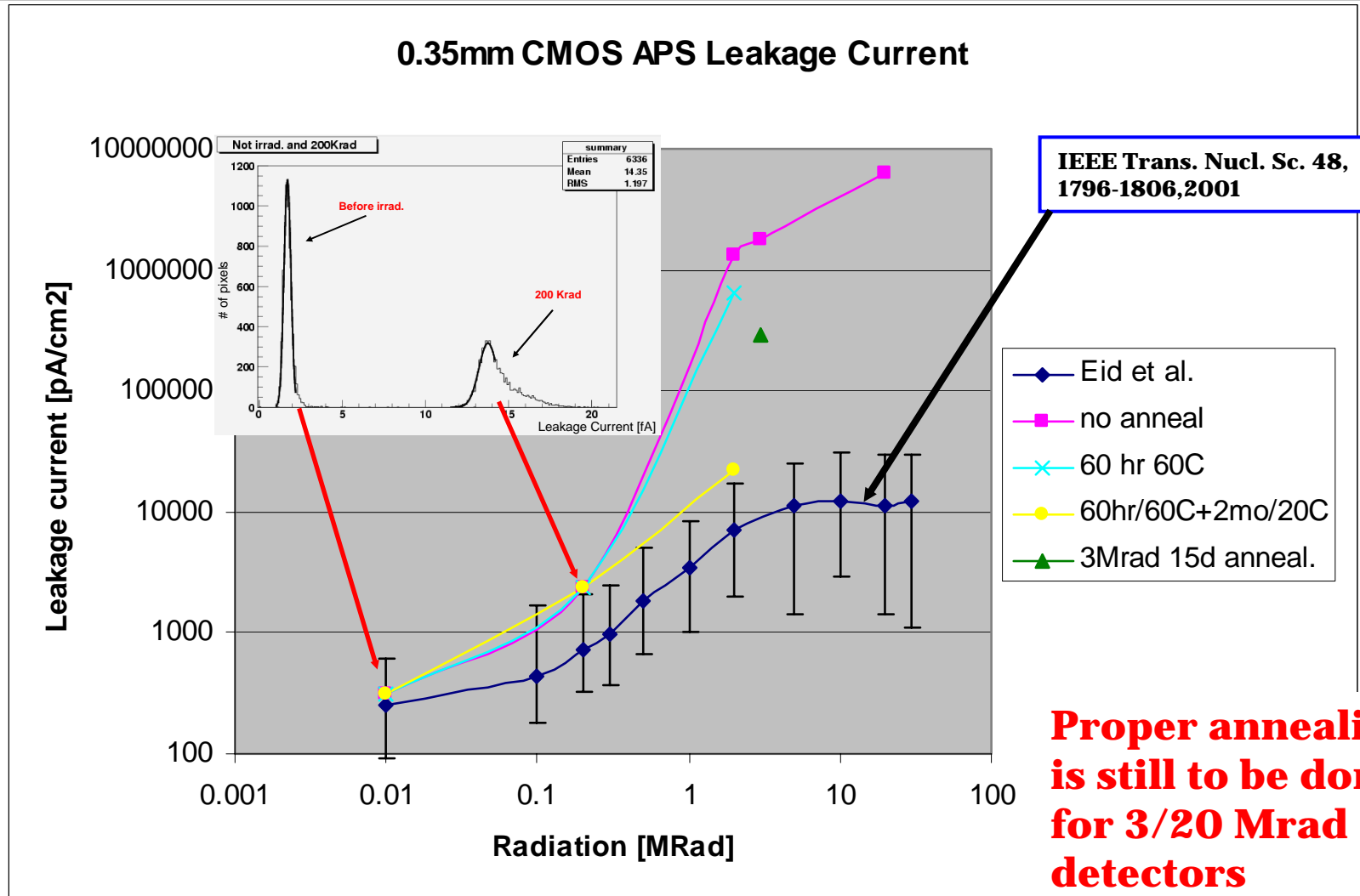
15 μ s operation of CAP2:

Current status:

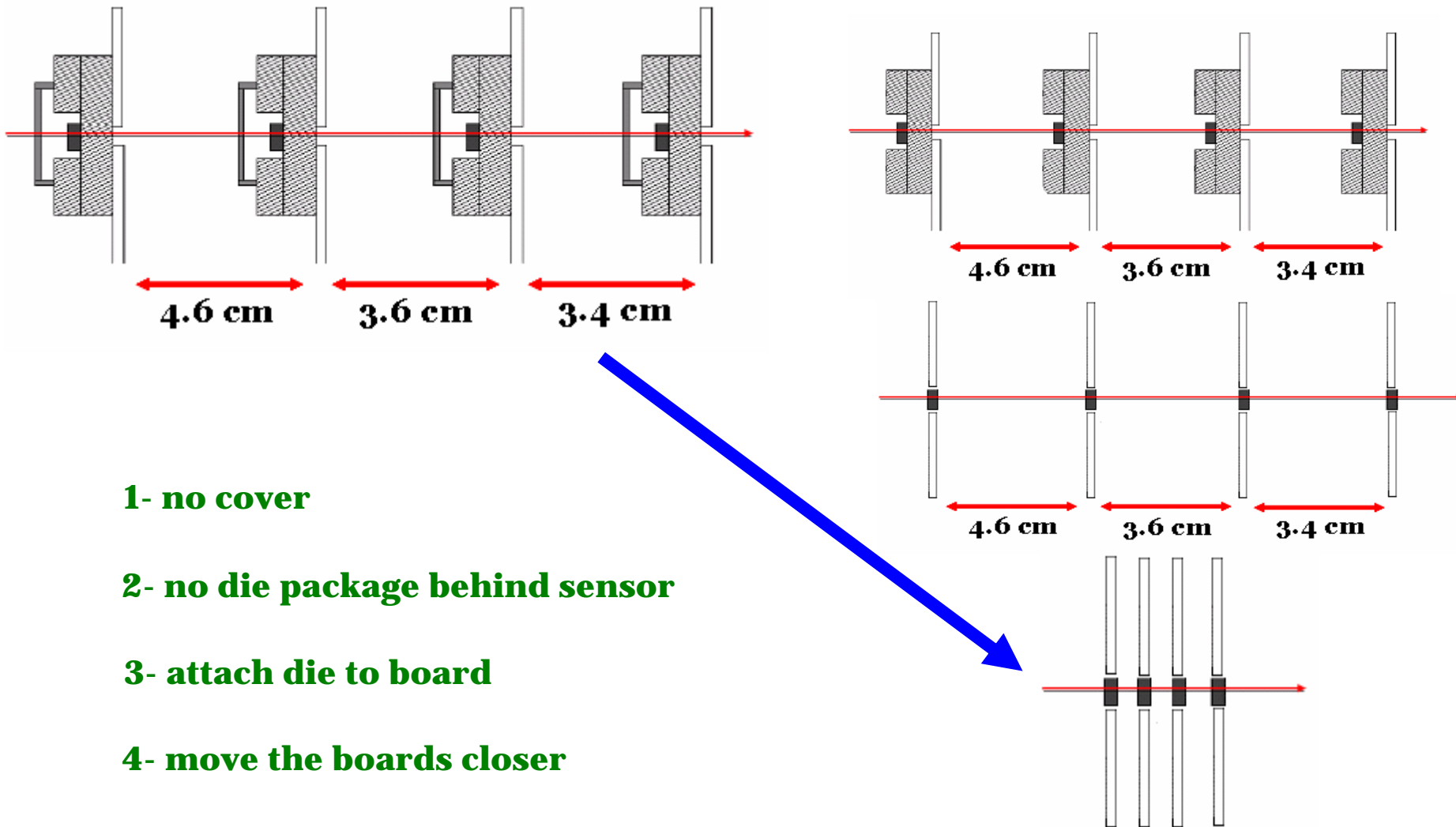
- **Noise higher** than what is observed with CAP1/F2/B2 (~30/~35e- vs. 16e-). **Related to digital activity?** → **Shield?**
- **Leakage current under control.**
- **Mini-pipeline output level dispersion rather large.** Not a dramatic problem, but can improved (by design). → **Modification in pipeline design?**
- **Still more work to be done on CAP2 testing.**



2. Irrad: leakage currents



Improving the UL on resolution?



1- no cover

2- no die package behind sensor

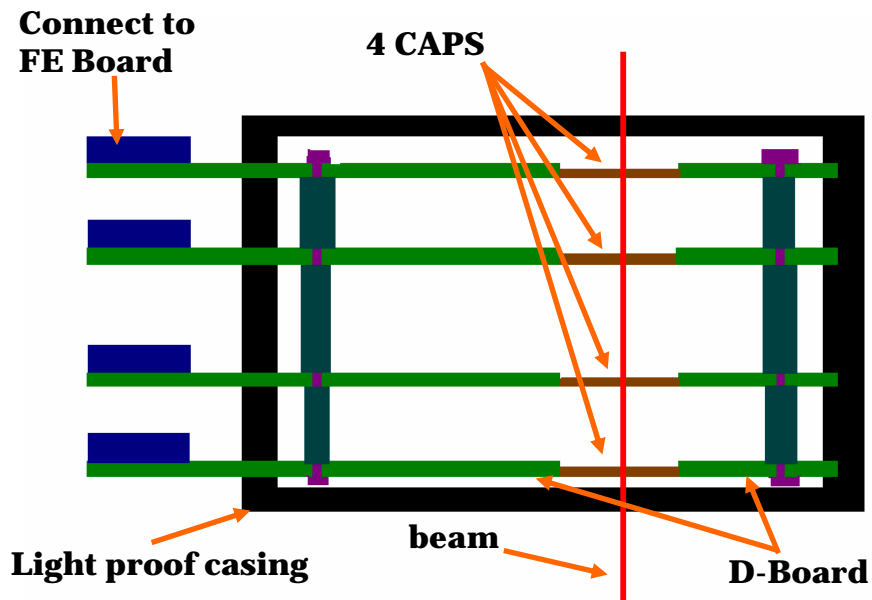
3- attach die to board

4- move the boards closer

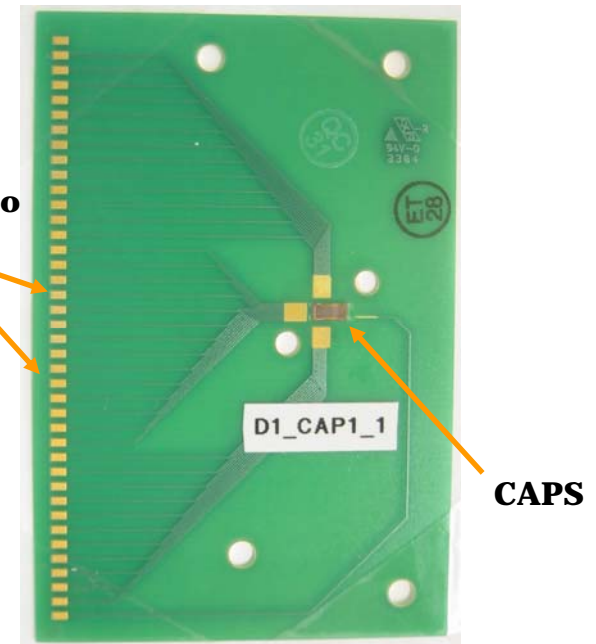


Improving the UL on hit resolution

- **Compact packaging for next beam test:**
 - **Expect a better upper limit on intrinsic resolution**

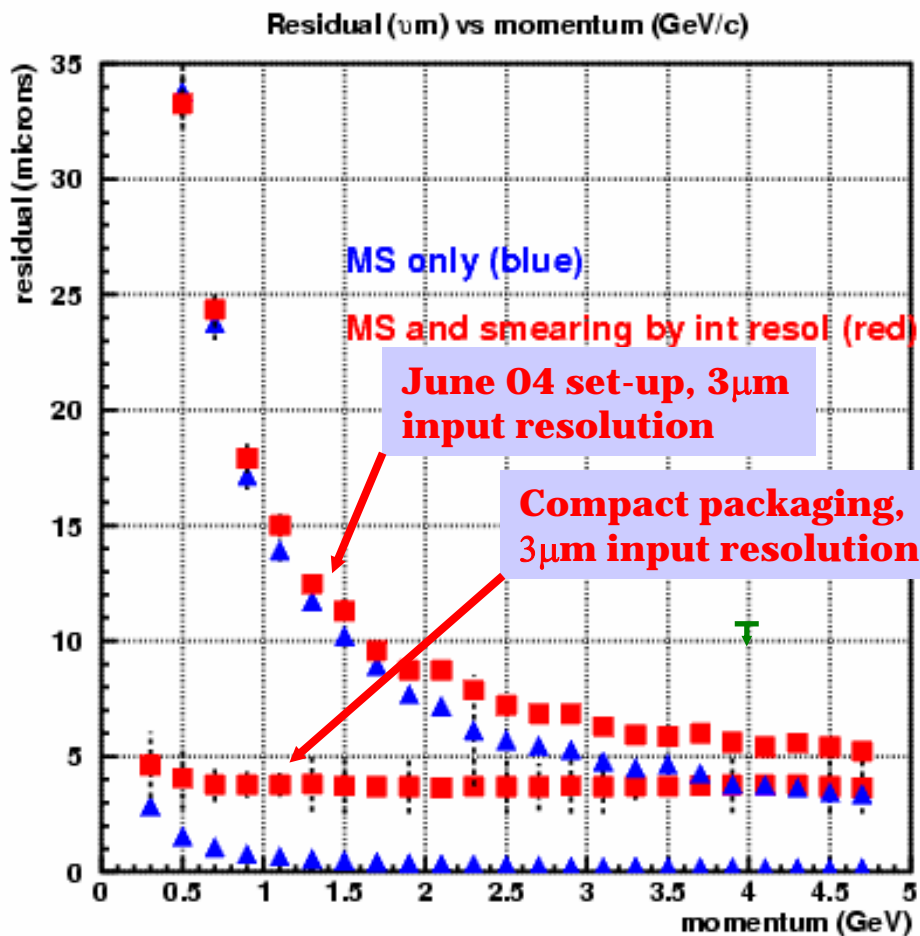


D-Board view from above



- Highlights:**
- **<0.3cm between CAPS.**
 - **reduced material**
 - **eases alignment.**

Hit resolution (GEANT simulations)



12 μm /20 μm IR for strips

@ 4GeV, 5-7 μm (as in June beam test configuration) \rightarrow 4 μm

Effects of multiple scattering and of distances become negligible!

Looking forward to next beam test



Highlights & Conclusion

MAPS is a promising technology for a Super-B Factory.

- **Successful beam test in June:**
 - **Experience gained / Demonstrate beam test operation.**
 - **UL on IR: $11\mu\text{m}$ / Charge spread: 90% in 4 pixels.**
- **CAP2 and next iterations:**
 - **Works alright, more work to be done → improvements.**
- **Further Radiation Damage Studies:**
 - **Still a hot topic but positive preliminary studies, we wait for new data points.**
 - **Demonstrate operation with highly irradiated detectors.**

**Have started to write down the basis for a future
Belle Pixel Vertex Detector 1.0 TDR.**

